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# AO4482

## 100V N-Channel MOSFET

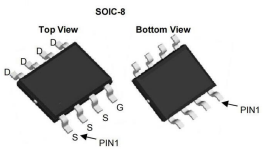
### General Description

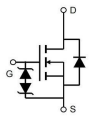
The AO4482 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

### Product Summary

| | |
|---|---|
| $V_{DS}$ | 100V |
| $I_D$ (at $V_{GS}$=10V) | 6A |
| $R_{DS(ON)}$ (at $V_{GS}$=10V) | < 37mΩ |
| $R_{DS(ON)}$ (at $V_{GS}$ = 4.5V) | < 42mΩ |

100% UIS Tested
100% $R_g$ Tested




| Orderable Part Number | Package Type | Form | Minimum Order Quantity |
|---|---|---|---|
| | SO-8 | Tape & Reel | 3000 |

**Absolute Maximum Ratings $T_A$=25℃ unless otherwise noted**

| Parameter | | Symbol | Maximum | Units |
|---|---|---|---|---|
| Drain-Source Voltage | | $V_{DS}$ | 100 | V |
| Gate-Source Voltage | | $V_{GS}$ | ±20 | V |
| Continuous Drain Current | $T_A$=25℃ | $I_D$ | 6 | A |
| | $T_A$=70℃ | | 5 | |
| Pulsed Drain Current [C] | | $I_{DM}$ | 42 | |
| Avalanche Current [C] | | $I_{AS}$, $I_{AR}$ | 35 | A |
| Avalanche energy L=0.1mH [C] | | $E_{AS}$, $E_{AR}$ | 61 | mJ |
| Power Dissipation [B] | $T_A$=25℃ | $P_D$ | 3.1 | W |
| | $T_A$=70℃ | | 2 | |
| Junction and Storage Temperature Range | | $T_J$, $T_{STG}$ | -55 to 150 | ℃ |

**Thermal Characteristics**

| Parameter | | Symbol | Typ | Max | Units |
|---|---|---|---|---|---|
| Maximum Junction-to-Ambient [A] | t ≤ 10s | $R_{\theta JA}$ | 31 | 40 | ℃/W |
| Maximum Junction-to-Ambient [A D] | Steady-State | | 59 | 75 | ℃/W |
| Maximum Junction-to-Lead | Steady-State | $R_{\theta JL}$ | 16 | 24 | ℃/W |

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**Electrical Characteristics ($T_J$=25℃ unless otherwise noted)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| **STATIC PARAMETERS** | | | | | | |
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $I_D$=250μA, $V_{GS}$=0V | 100 | | | V |
| $I_{DSS}$ | Zero Gate Voltage Drain Current | $V_{DS}$=100V, $V_{GS}$=0V | | | 1 | μA |
| | | $T_J$=55℃ | | | 5 | |
| $I_{GSS}$ | Gate-Body leakage current | $V_{DS}$=0V, $V_{GS}$= ±20V | | | 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$=$V_{GS}$ $I_D$=250μA | 1.6 | 2.1 | 2.7 | V |
| $I_{D(ON)}$ | On state drain current | $V_{GS}$=10V, $V_{DS}$=5V | 42 | | | A |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}$=10V, $I_D$=6A | | 30 | 37 | mΩ |
| | | $T_J$=125℃ | | 60 | 72 | |
| | | $V_{GS}$=4.5V, $I_D$=5A | | 33 | 42 | mΩ |
| $g_{FS}$ | Forward Transconductance | $V_{DS}$=5V, $I_D$=6A | | 35 | | S |
| $V_{SD}$ | Diode Forward Voltage | $I_S$=1A,$V_{GS}$=0V | | 0.7 | 1 | V |
| $I_S$ | Maximum Body-Diode Continuous Current | | | | 4 | A |
| **DYNAMIC PARAMETERS** | | | | | | |
| $C_{iss}$ | Input Capacitance | $V_{GS}$=0V, $V_{DS}$=50V, f=1MHz | 1300 | 1630 | 2000 | pF |
| $C_{oss}$ | Output Capacitance | | 70 | 100 | 130 | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | 30 | 50 | 70 | pF |
| $R_g$ | Gate resistance | $V_{GS}$=0V, $V_{DS}$=0V, f=1MHz | 0.3 | 0.75 | 1.1 | Ω |
| **SWITCHING PARAMETERS** | | | | | | |
| $Q_g$(10V) | Total Gate Charge | $V_{GS}$=10V, $V_{DS}$=50V, $I_D$=6A | 28 | 36 | 44 | nC |
| $Q_g$(4.5V) | Total Gate Charge | | 14 | 18 | 22 | nC |
| $Q_{gs}$ | Gate Source Charge | | 4 | 5 | 6 | nC |
| $Q_{gd}$ | Gate Drain Charge | | 5 | 9 | 13 | nC |
| $t_{D(on)}$ | Turn-On DelayTime | $V_{GS}$=10V, $V_{DS}$=50V, $R_L$=8.3Ω, $R_{GEN}$=3Ω | | 7 | | ns |
| $t_r$ | Turn-On Rise Time | | | 7 | | ns |
| $t_{D(off)}$ | Turn-Off DelayTime | | | 28 | | ns |
| $t_f$ | Turn-Off Fall Time | | | 7 | | ns |
| $t_{rr}$ | Body Diode Reverse Recovery Time | $I_F$=6A, dI/dt=500A/μs | 17.5 | 25 | 33 | ns |
| $Q_{rr}$ | Body Diode Reverse Recovery Charge | $I_F$=6A, dI/dt=500A/μs | 90 | 130 | 170 | nC |

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in$^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A$ =25℃. The value in any given application depends on the user's specific board design.

B. The power dissipation $P_D$ is based on $T_{J(MAX)}$=150℃, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150℃. Ratings are based on low frequency and duty cycles to keep initial$T_J$=25℃.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedence which is measured with the device mounted on 1in$^2$ FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}$=150℃. The SOA curve provides a single pulse ratin g.

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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

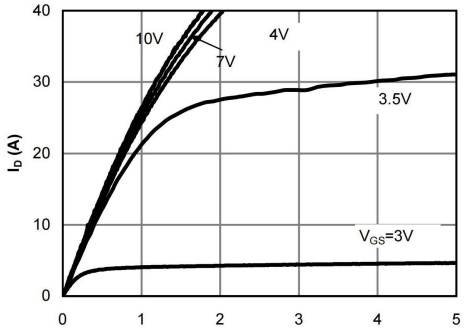



Fig 1: On-Region Characteristics (Note E)

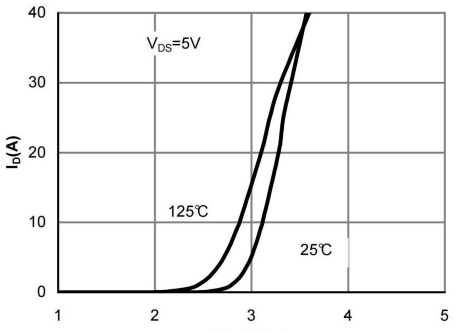



Figure 2: Transfer Characteristics (Note E)

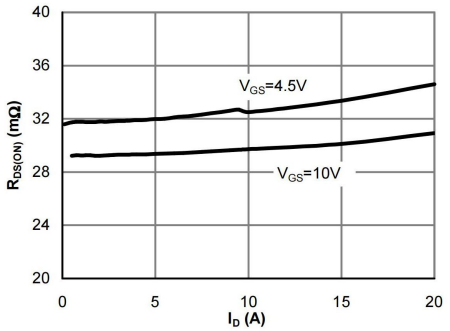



Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

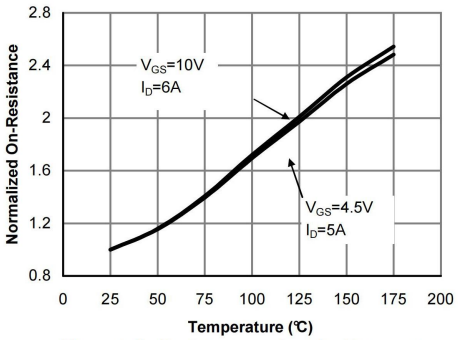



Figure 4: On-Resistance vs. Junction Temperature (Note E)

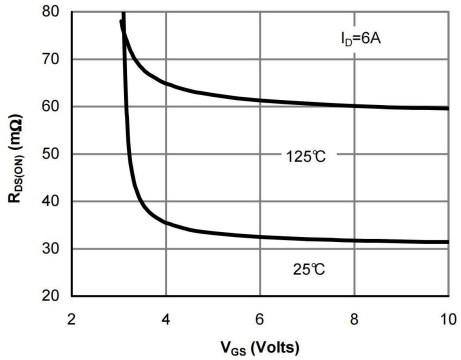



Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

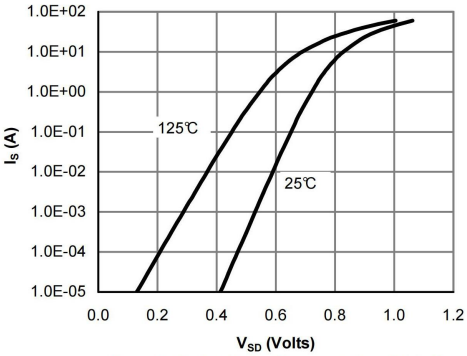



Figure 6: Body-Diode Characteristics (Note E)

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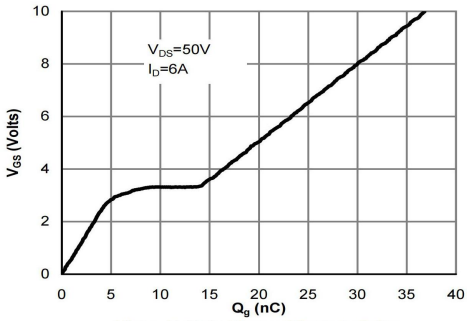



Figure 7: Gate-Charge Characteristics

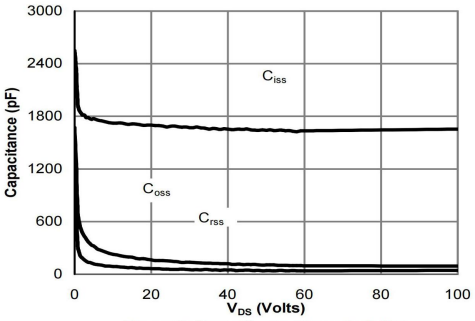



Figure 8: Capacitance Characteristics

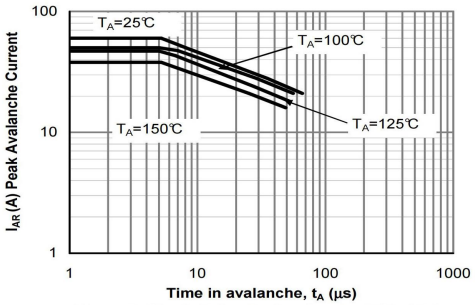



Figure 9: Single Pulse Avalanche capability (Note C)

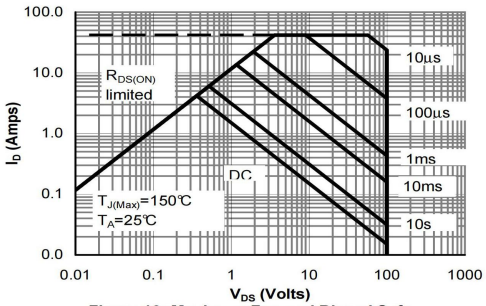



Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

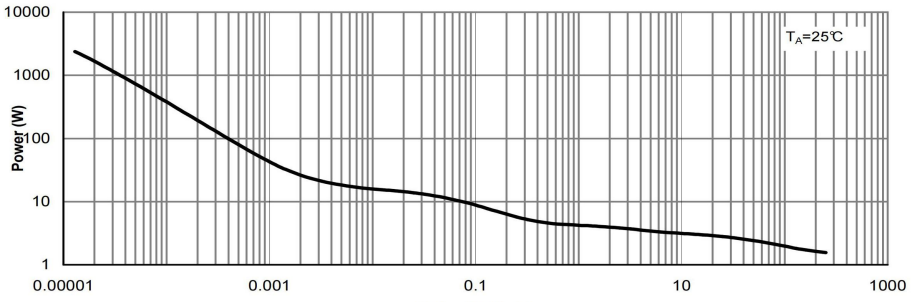



Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

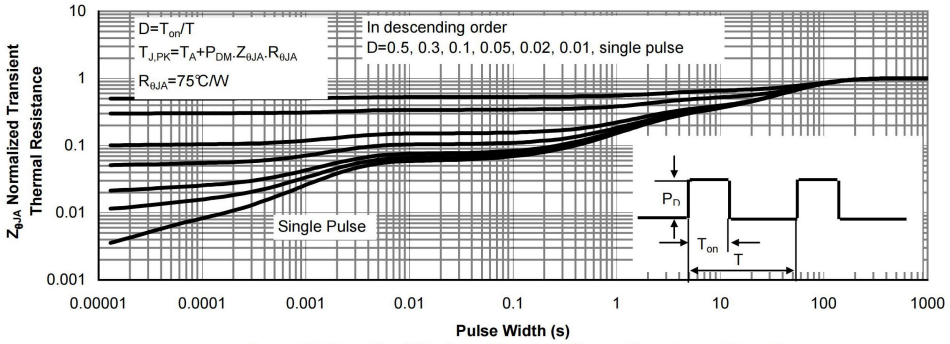
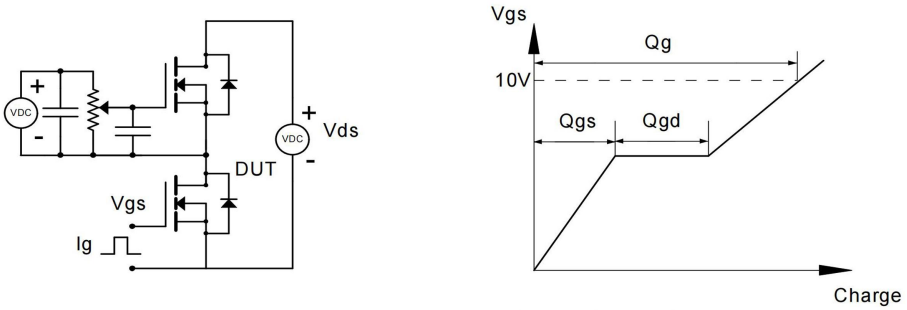


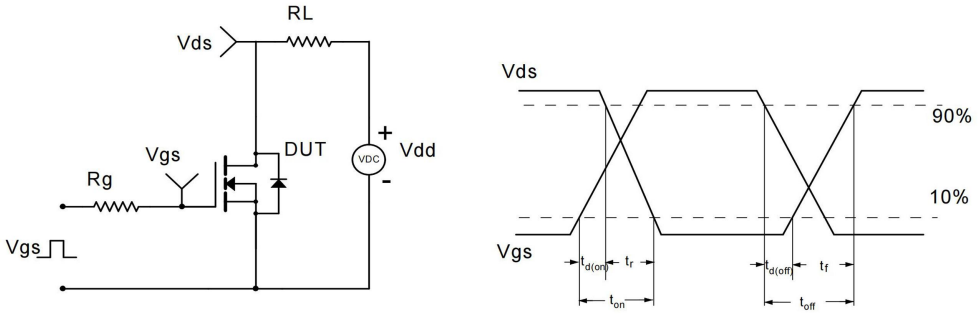

Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

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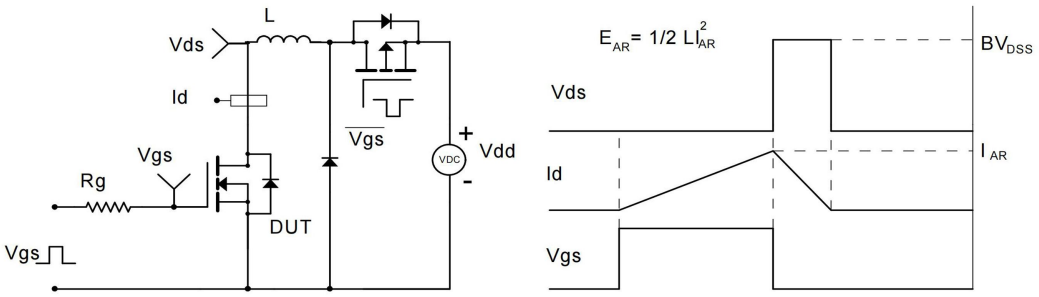
Gate Charge Test Circuit & Waveform




Resistive Switching Test Circuit & Waveforms




Unclamped Inductive Switching (UIS) Test Circuit & Waveforms




Diode Recovery Test Circuit & Waveforms

